

**Assembly Transfer of Select BGA Products and Conversion
to CSP_BGA to STATS ChipPAC Korea**

**Qualification Results Summary for
CSP_BGA at STATS ChipPAC Korea**

TEST	SPECIFICATION	SAMPLE SIZE	RESULTS
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 77	Pass
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	Pass
Temperature Humidity Bias (THB)*	JEDEC <i>JESD22-A101</i>	3 x 77	Pass
High Temperature Storage (HTS)	JEDEC <i>JESD22-A103</i>	1 x 45	Pass
Unbiased Highly Accelerated Stress Test (UHAST)*	JEDEC <i>JESD22-A118</i>	3 x 77	Pass

* These samples will be subjected to preconditioning (per J-STD-020 Level 3) prior to the start of the stress test. Level 3 preconditioning consists of the following: 1. Bake – 24 hours at 125°C; 2. Soak – unbiased soak for 192 hours at 30°C, 60%RH; 3. Reflow – three passes through a reflow oven with a peak temperature of 260°C. TC samples will be subjected to wire-pull test after 500 cycles where results should be within specification limits.